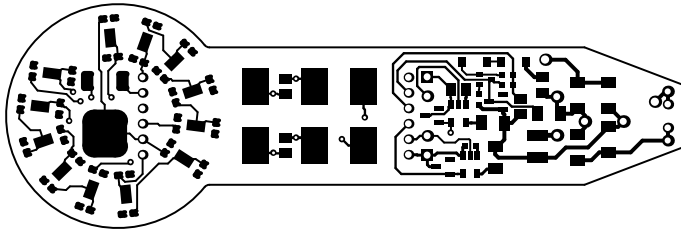
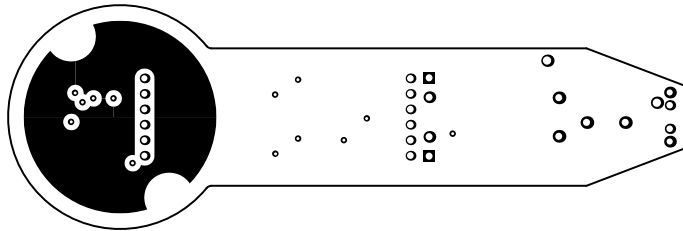


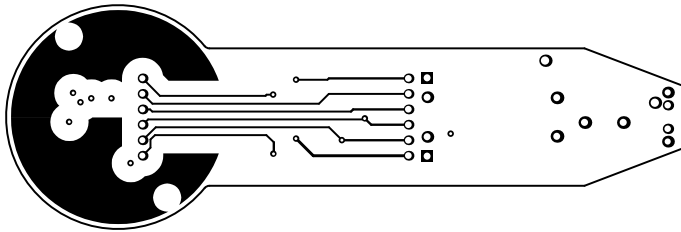
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP6025	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 1/5/2015 10:52:07 AM	TEXAS INSTRUMENTS	



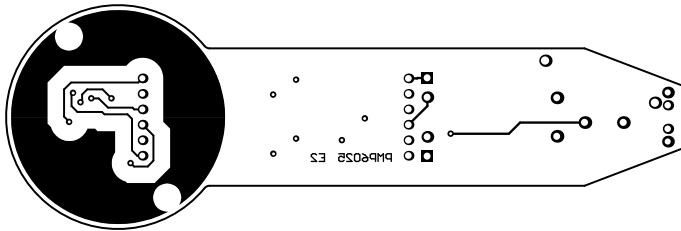
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP6025	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 1/5/2015 10:52:08 AM	TEXAS INSTRUMENTS	



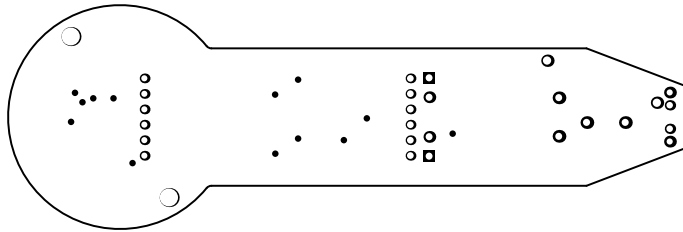
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP6025	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = MidLayer1			
PLOT NAME = MidLayer1	GENERATED : 1/5/2015 10:52:10 AM	TEXAS INSTRUMENTS	



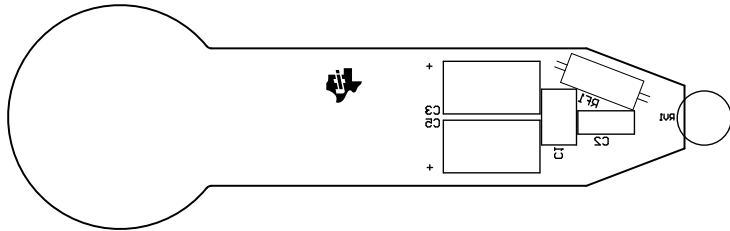
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP6025	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = MidLayer2			
PLOT NAME = MidLayer2	GENERATED : 1/5/2015 10:52:11 AM	TEXAS INSTRUMENTS	



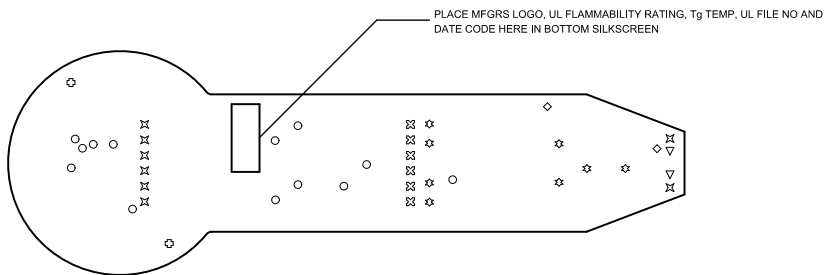
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP6025	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 1/5/2015 10:52:13 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP6025	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 1/5/2015 10:52:15 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP6025	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 1/5/2015	10:52:16 AM	TEXAS INSTRUMENTS



Symbol	Hit Count	Tool Size	Plated	Hole Type
○	13	16mil (0.406mm)	PTH	Round
⊗	8	32mil (0.813mm)	PTH	Round
▽	2	33.465mil (0.85mm)	PTH	Round
⊗	6	35mil (0.889mm)	PTH	Round
☆	8	37mil (0.94mm)	PTH	Round
◇	2	43.307mil (1.1mm)	PTH	Round
⊗	2	93mil (2.362mm)	NPTH	Round
41 Total				

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP6025	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 1/5/2015	10:52:18 AM	TEXAS INSTRUMENTS

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